24AA515/24LC515/24FC515

512K I²C™ CMOS Serial EEPROM

Device Selection Table

Part Number	Vcc Range	Max. Clock Frequency	Temp. Ranges
24AA515	1.8-5.5V	400 kHz†	I
24LC515	2.5-5.5V	400 kHz	I
24FC515	2.5-5.5V	1 MHz	I

†100 kHz for VCC < 2.5V.

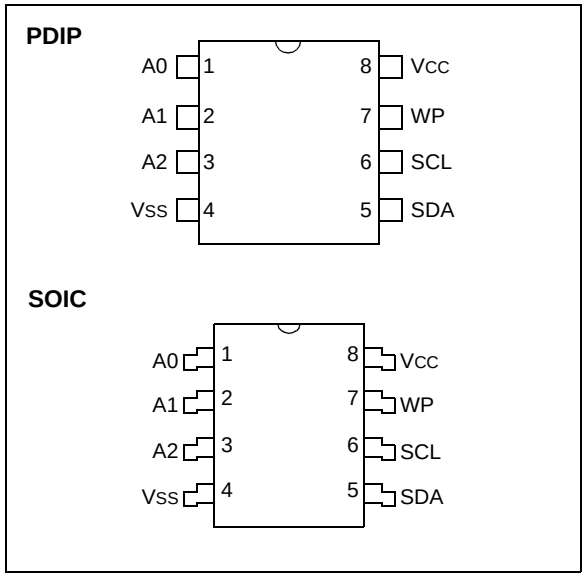
Features:

- Low-power CMOS technology:
  - Maximum write current 3 mA at 5.5V
  - Maximum read current 500 µA at 5.5V
  - Standby current 100 nA, typical at 5.5V
- 2-wire serial interface bus, I²C™ compatible
- Cascadable for up to four devices
- Self-timed erase/write cycle
- 64-byte Page Write mode available
- 5 ms max. write cycle time
- Hardware write-protect for entire array
- Output slope control to eliminate ground bounce
- Schmitt Trigger inputs for noise suppression
- 100,000 erase/write cycles
- Electrostatic discharge protection > 4000V
- Data retention > 200 years
- 8-pin PDIP, SOIC packages
- Temperature ranges:
  - Industrial (I): -40°C to +85°C

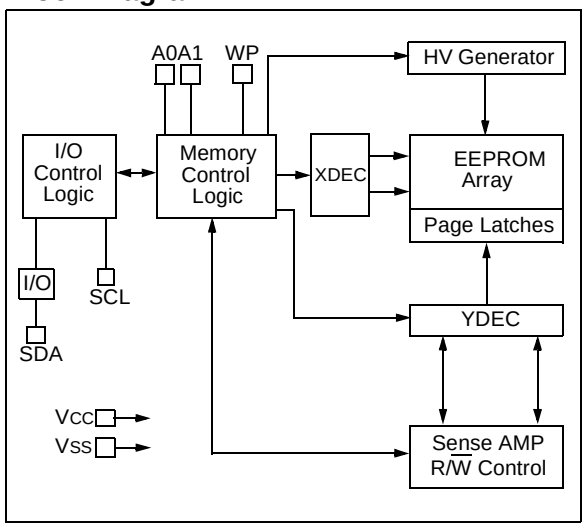
Description:

The Microchip Technology Inc. 24AA515/24LC515/24FC515 (24XX515*) is a 64K x 8 (512K bit) Serial Electrically Erasable PROM, capable of operation across a broad voltage range (1.8V to 5.5V). It has been developed for advanced, low power applications such as personal communications or data acquisition. This device has both byte write and page write capability of up to 64 bytes of data. This device is capable of both random and sequential reads. Reads may be sequential within address boundaries 0000h to 7FFFh and 8000h to FFFFh. Functional address lines allow up to four devices on the same data bus. This allows for up to 2 Mbits total system EEPROM memory. This device is available in the standard 8-pin plastic DIP and SOIC packages.

Package Type



Block Diagram



*24XX515 is used in this document as a generic part number for the 24AA515/24LC515/24FC515 devices.

© 2005 Microchip Technology Inc.

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

V_{CC}.....6.5V

All inputs and outputs w.r.t. V_{SS} ..... -0.6V to V_{CC} +1.0V

Storage temperature .....-65°C to +150°C

Ambient temperature with power applied.....-40°C to +125°C

ESD protection on all pins .....≥ 4 kV

† NOTICE**:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: DC CHARACTERISTICS

DC CHARACTERISTICS			Industrial (I): V_{CC} = +1.8V to 5.5V T_A = -40°C to +85°C			
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
		A0, A1, SCL, SDA and WP pins:				
D1	V_{IH}	High-level input voltage	0.7 V_{CC}	—	V	
D2	V_{IL}	Low-level input voltage	—	0.3 V_{CC} 0.2 V_{CC}	V V	$V_{CC} \geq$ 2.5V V_{CC} < 2.5V
D3	V_{HYS}	Hysteresis of Schmitt Trigger inputs (SDA, SCL pins)	0.05 V_{CC}	—	V	$V_{CC} \geq$ 2.5V **(Note)**
D4	V_{OL}	Low-level output voltage	—	0.40	V	I_{OL} = 3.0 mA @ V_{CC} = 4.5V I_{OL} = 2.1 mA @ V_{CC} = 2.5V
D5	I_{LI}	Input leakage current	—	±1	µA	V_{IN} = V_{SS} or V_{CC}, WP = V_{SS} V_{IN} = V_{SS} or V_{CC}, WP = V_{CC}
D6	I_{LO}	Output leakage current	—	±1	µA	V_{OUT} = V_{SS} or V_{CC}
D7	C_{IN}, C_{OUT}	Pin capacitance (all inputs/outputs)	—	10	pF	V_{CC} = 5.0V **(Note)** T_A = 25°C, F_{CLK} = 1 MHz
D8	I_{CC} Read	Operating current	—	500	µA	V_{CC} = 5.5V, SCL = 400 kHz
	I_{CC} Write		—	3	mA	V_{CC} = 5.5V
D9	Iccs	Standby current	—	5	µA	SCL = SDA = V_{CC} = 5.5V A0, A1, WP = V_{SS}, A2 = V_{CC}

Note: This parameter is periodically sampled and not 100% tested.

© 2005 Microchip Technology Inc.

TABLE 1-2: AC CHARACTERISTICS

AC CHARACTERISTICS			Industrial (I): V_{CC} = +1.8V to 5.5V T_A = -40°C to +85°C			
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
1	F_{CLK}	Clock frequency	— — —	100 400 1000	kHz	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
2	T_{HIGH}	Clock high time	4000 600 500	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
3	T_{LOW}	Clock low time	4700 1300 500	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
4	T_R	SDA and SCL rise time **(Note 1)**	— — —	1000 300 300	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
5	T_F	SDA and SCL fall time **(Note 1)**	— —	300 100	ns	All except, 24FC515 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
6	$T_{HD:STA}$	Start condition hold time	4000 600 250	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
7	$T_{SU:STA}$	Start condition setup time	4700 600 250	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
8	$T_{HD:DAT}$	Data input hold time	0	—	ns	**(Note 2)**
9	$T_{SU:DAT}$	Data input setup time	250 100 100	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
10	$T_{SU:STO}$	Stop condition setup time	4000 600 250	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
11	$T_{SU:WP}$	WP setup time	4000 600 600	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
12	$T_{HD:WP}$	WP hold time	4700 1300 1300	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
13	T_{AA}	Output valid from clock **(Note 2)**	— — —	3500 900 400	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
14	T_{BUF}	Bus free time: Time the bus must be free before a new transmission can start	4700 1300 500	— — —	ns	1.8V ≤ V_{CC} ≤ 2.5V 2.5V ≤ V_{CC} ≤ 5.5V 2.5V ≤ V_{CC} ≤ 5.5V (24FC515 only)
15	T_{OF}	Output fall time from V_{IH} minimum to V_{IL} maximum C_B ≤ 100 pF	10 + 0.1C_B	250 250	ns	All except, 24FC515 **(Note 1)** 24FC515 **(Note 1)**
16	T_{SP}	Input filter spike suppression (SDA and SCL pins)	—	50	ns	All except, 24FC515 **(Notes 1 and 3)**
17	T_{WC}	Write cycle time (byte or page)	—	5	ms	
18		Endurance	1 M	—	cycles	25°C **(Note 4)**

Note 1: Not 100% tested. C_B = total capacitance of one bus line in pF.

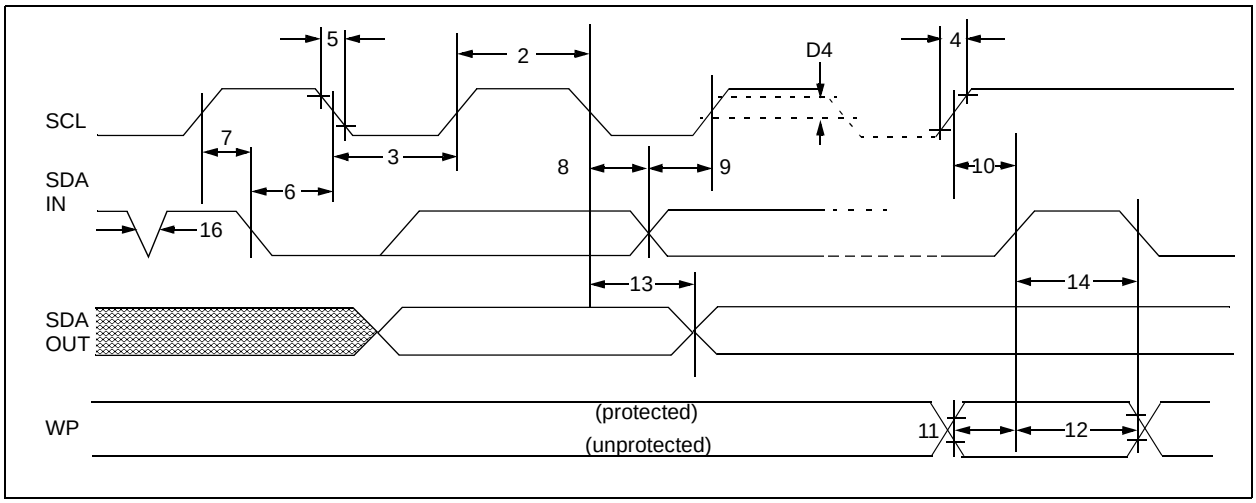
2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

3: The combined T_{SP} and V_{HYS} specifications are due to new Schmitt Trigger inputs which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.

4: This parameter is not tested but established by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained from Microchip's web site at www.microchip.com.

© 2005 Microchip Technology Inc.

FIGURE 1-1: BUS TIMING DATA



© 2005 Microchip Technology Inc.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Name	PDIP	SOIC	Function
A0	1	1	User Configurable Chip Select
A1	2	2	User Configurable Chip Select
A2	3	3	Non-Configurable Chip Select. This pin must be hard wired to logical 1 state (VCC). Device will not operate with this pin left floating or held to logical 0 (VSS).
VSS	4	4	Ground
SDA	5	5	Serial Data
SCL	6	6	Serial Clock
WP	7	7	Write-Protect Input
VCC	8	8	+1.8 to 5.5V (24AA515) +2.5 to 5.5V (24LC515) +2.5 to 5.5V (24FC515)

2.1 A0, A1 Chip Address Inputs

The A0, A1 inputs are used by the 24XX515 for multiple device operations. The levels on these inputs are compared with the corresponding bits in the slave address. The chip is selected if the compare is true.

Up to four devices may be connected to the same bus by using different Chip Select bit combinations. In most applications, the chip address inputs A0 and A1 are hard-wired to logic '0' or logic '1'. For applications in which these pins are controlled by a microcontroller or other programmable device, the chip address pins must be driven to logic '0' or logic '1' before normal device operation can proceed.

2.2 A2 Chip Address Input

The A2 input is non-configurable Chip Select. This pin must be tied to VCC in order for this device to operate.

2.3 Serial Data (SDA)

This is a bidirectional pin used to transfer addresses and data into and data out of the device. It is an open-drain terminal, therefore, the SDA bus requires a pull-up resistor to VCC (typical 10 kΩ for 100 kHz, 2 kΩ for 400 kHz and 1 MHz).

For normal data transfer SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the Start and Stop conditions.

2.4 Serial Clock (SCL)

This input is used to synchronize the data transfer from and to the device.

2.5 Write-Protect (WP)

This pin must be connected to either VSS or VCC. If tied to VSS, write operations are enabled. If tied to VCC, write operations are inhibited but read operations are not affected.

3.0 FUNCTIONAL DESCRIPTION

The 24XX515 supports a bidirectional 2-wire bus and data transmission protocol. A device that sends data onto the bus is defined as a transmitter, and a device receiving data as a receiver. The bus must be controlled by a master device which generates the Serial Clock (SCL), controls the bus access, and generates the Start and Stop conditions while the 24XX515 works as a slave. Both master and slave can operate as a transmitter or receiver, but the master device determines which mode is activated.

4.0 BUS CHARACTERISTICS

The following **bus protocol** has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is high. Changes in the data line while the clock line is high will be interpreted as a Start or Stop condition.

Accordingly, the following bus conditions have been defined (Figure 4-1).

4.1 Bus Not Busy (A)

Both data and clock lines remain high.

4.2 Start Data Transfer (B)

A high-to-low transition of the SDA line while the clock (SCL) is high determines a Start condition. All commands must be preceded by a Start condition.

4.3 Stop Data Transfer (C)

A low-to-high transition of the SDA line while the clock (SCL) is high determines a Stop condition. All operations must end with a Stop condition.

4.4 Data Valid (D)

The state of the data line represents valid data when, after a Start condition, the data line is stable for the duration of the high period of the clock signal.

The data on the line must be changed during the low period of the clock signal. There is one bit of data per clock pulse.

Each data transfer is initiated with a Start condition and terminated with a Stop condition. The number of the data bytes transferred between the Start and Stop conditions is determined by the master device.

4.5 Acknowledge

Each receiving device, when addressed, is obliged to generate an Acknowledge signal after the reception of each byte. The master device must generate an extra clock pulse which is associated with this Acknowledge bit.

Note:	The 24XX515 does not generate any Acknowledge bits if an internal programming cycle is in progress, however, the control byte that is being polled must match the control byte used to initiate the write cycle.

A device that acknowledges must pull-down the SDA line during the Acknowledge clock pulse in such a way that the SDA line is stable low during the high period of the acknowledge related clock pulse. Of course, setup and hold times must be taken into account. During reads, a master must signal an end of data to the slave by NOT generating an Acknowledge bit on the last byte that has been clocked out of the slave. In this case, the slave (24XX515) will leave the data line high to enable the master to generate the Stop condition.

FIGURE 4-1: DATA TRANSFER SEQUENCE ON THE SERIAL BUS

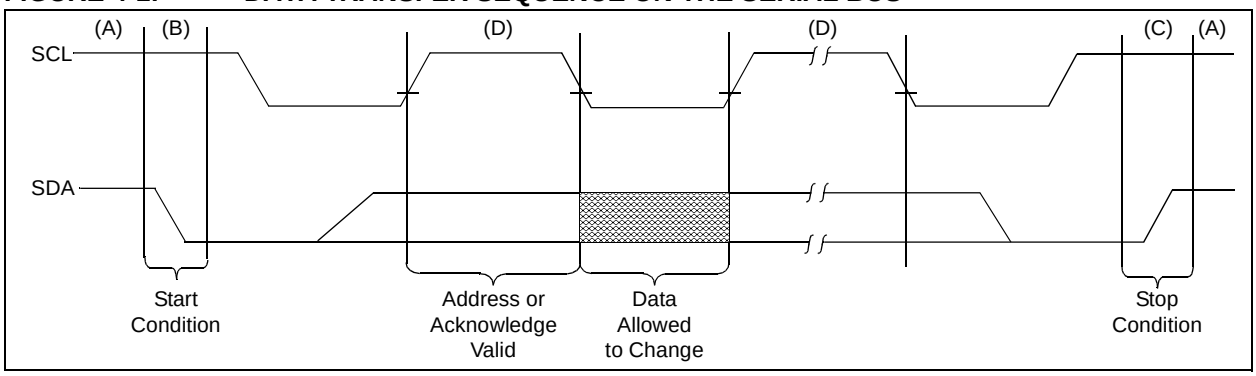
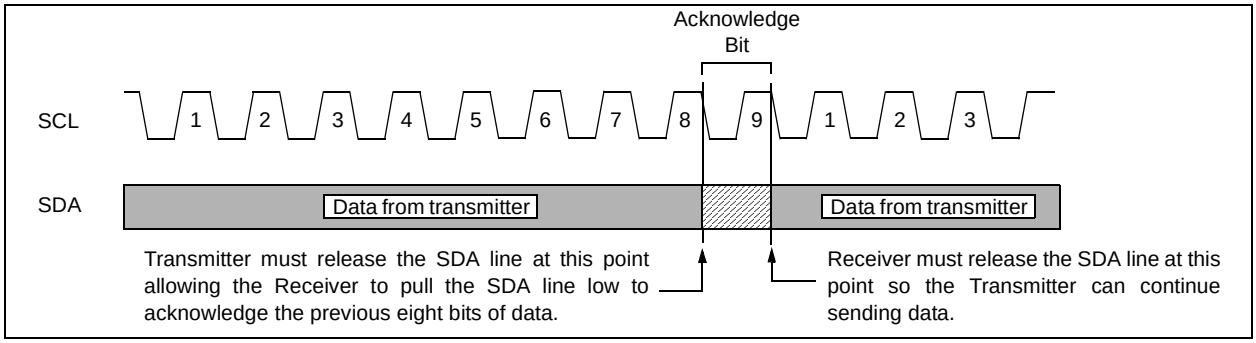


FIGURE 4-2: ACKNOWLEDGE TIMING



© 2005 Microchip Technology Inc.

5.0 DEVICE ADDRESSING

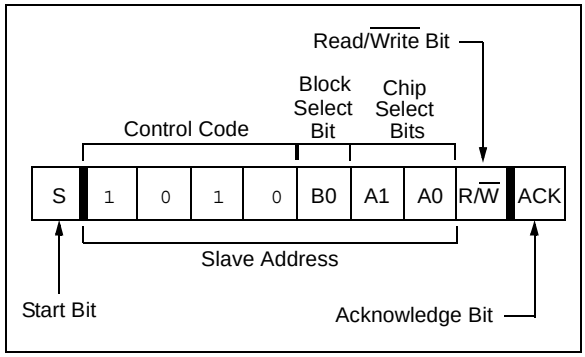
A control byte is the first byte received following the Start condition from the master device (Figure 5-1). The control byte consists of a 4-bit control code; for the 24XX515, this is set as '1010' binary for read and write operations. The next bit of the control byte is the block select bit (B0). This bit acts as the A15 address bit for accessing the entire array. The next two bits of the control byte are the Chip Select bits (A1, A0). The Chip Select bits allow the use of up to four 24XX515 devices on the same bus and are used to select which device is accessed. The Chip Select bits in the control byte must correspond to the logic levels on the corresponding A1 and A0 pins for the device to respond. These bits are in effect the two Most Significant bits of the word address.

The last bit of the control byte defines the operation to be performed. When set to a '1', a read operation is selected, and when set to a '0', a write operation is selected. The next two bytes received define the address of the first data byte (Figure 5-2). Because only A14…A0 are used, the upper address bit is a "don't care." The upper address bits are transferred first, followed by the Less Significant bits.

Following the Start condition, the 24XX515 monitors the SDA bus checking the device type identifier being transmitted. Upon receiving a '1010' code and appropriate device select bits, the slave device outputs an Acknowledge signal on the SDA line. Depending on the state of the R/$\overline{W}$ bit, the 24XX515 will select a read or write operation.

This device has an internal addressing boundary limitation that is divided into two segments of 256K bits. Block select bit 'B0' is used in place of address bit location 'A15' to control access to each segment.

FIGURE 5-1: CONTROL BYTE FORMAT



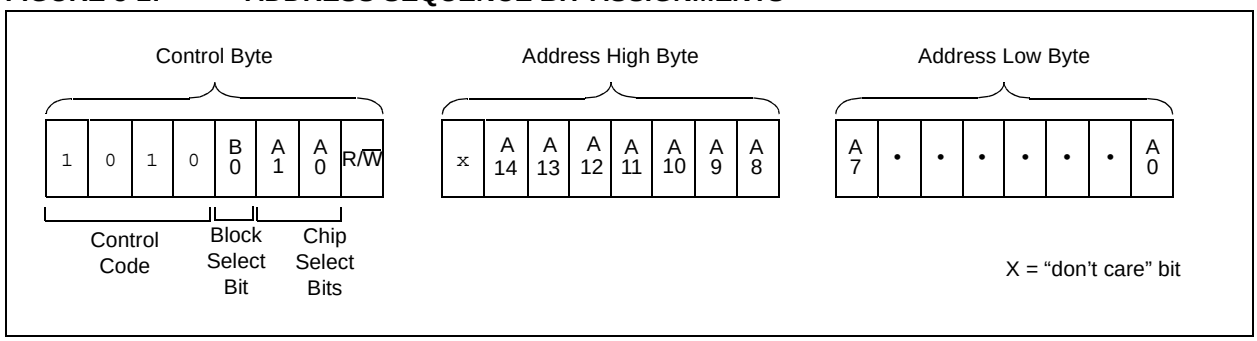
5.1 Contiguous Addressing Across Multiple Devices

The Chip Select bits A1, A0 can be used to expand the contiguous address space for up to 2 Mbit by adding up to four 24XX515's on the same bus. In this case, software can use A0 of the control byte as address bit A16 and A1 as address bit A17. It is not possible to sequentially read across device boundaries.

Each device has internal addressing boundary limitations. This divides each part into two segments of 256K bits. The block select bit 'B0' controls access to each "half" rather than address bit location A15.

Sequential read operations are limited to 256K blocks. To read through four devices on the same bus, eight random Read commands must be given.

FIGURE 5-2: ADDRESS SEQUENCE BIT ASSIGNMENTS



6.0 WRITE OPERATIONS

6.1 Byte Write

Following the Start condition from the master, the control code (four bits), the block select (one bit) the Chip Select (two bits), and the R/$\overline{W}$ bit (which is a logic low) are clocked onto the bus by the master transmitter. This indicates to the addressed slave receiver that the address high byte will follow after it has generated an Acknowledge bit during the ninth clock cycle. Therefore, the next byte transmitted by the master is the high-order byte of the word address and will be written into the Address Pointer of the 24XX515. The next byte is the Least Significant Address Byte. After receiving another Acknowledge signal from the 24XX515, the master device will transmit the data word to be written into the addressed memory location. The 24XX515 acknowledges again and the master generates a Stop condition. This initiates the internal write cycle and during this time, the 24XX515 will not generate Acknowledge signals as long as the control byte being polled matches the control byte that was used to initiate the write (Figure 6-1). If an attempt is made to write to the array with the WP pin held high, the device will acknowledge the command but no write cycle will occur, no data will be written, and the device will immediately accept a new command. After a byte Write command, the internal address counter will point to the address location following the one that was just written.

6.2 Page Write

The write control byte, word address, and the first data byte are transmitted to the 24XX515 in the same way as in a byte write. But instead of generating a Stop condition, the master transmits up to 63 additional bytes, which are temporarily stored in the on-chip page buffer and will be written into memory after the master has transmitted a Stop condition. After receipt of each word, the six lower Address Pointer bits are internally incremented by one. If the master should transmit more than 64 bytes prior to generating the Stop condition, the address counter will roll over and the previously received data will be overwritten. As with the byte write operation, once the Stop condition is received, an internal write cycle will begin (Figure 6-2). If an attempt is made to write to the array with the WP pin held high, the device will acknowledge the command but no write cycle will occur, no data will be written, and the device will immediately accept a new command.

6.3 Write Protection

The WP pin allows the user to write-protect the entire array (0000-FFFF) when the pin is tied to VCC. If tied to VSS the write protection is disabled. The WP pin is sampled at the Stop bit for every Write command (Figure 1-1) Toggling the WP pin after the Stop bit will have no effect on the execution of the write cycle.

Note:	Page write operations are limited to writing bytes within a single physical page, regardless of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page size') and end at addresses that are integer multiples of [page size – 1]. If a Page Write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

© 2005 Microchip Technology Inc.

FIGURE 6-1: BYTE WRITE

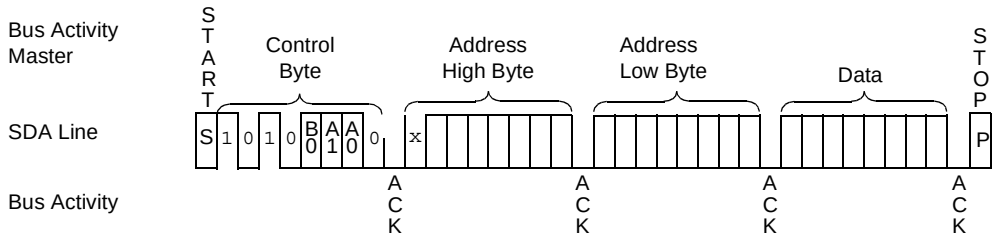
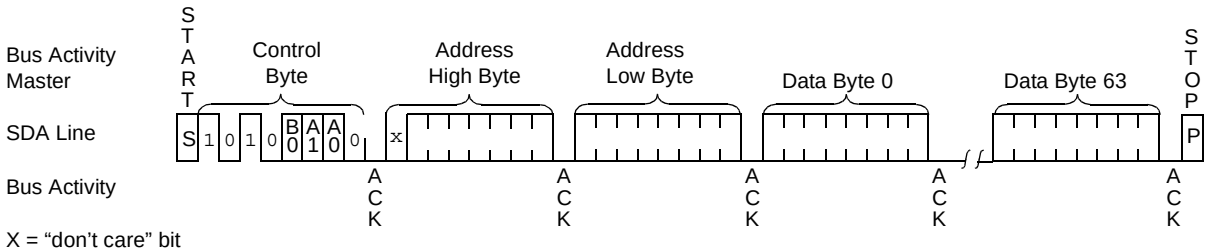


FIGURE 6-2: PAGE WRITE

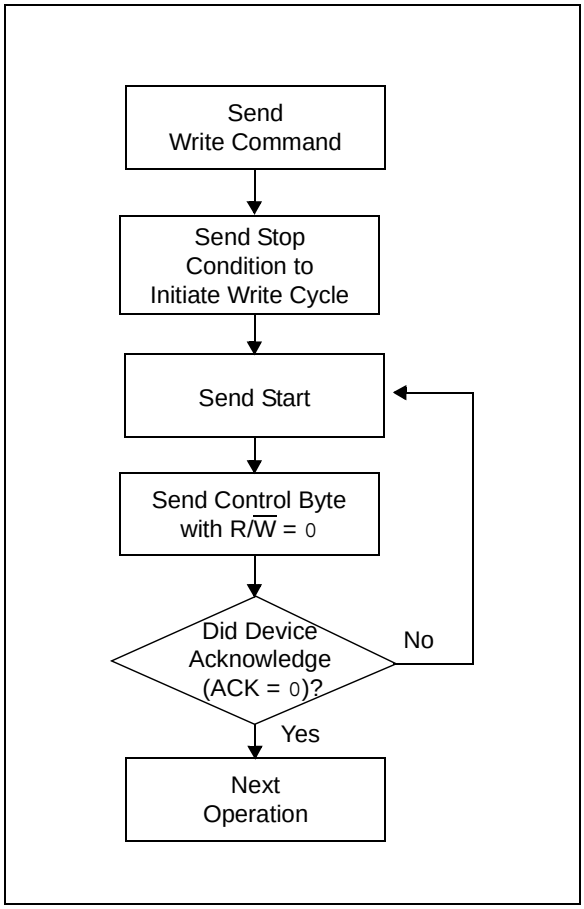


7.0 ACKNOWLEDGE POLLING

Since the device will not acknowledge during a write cycle, this can be used to determine when the cycle is complete. (This feature can be used to maximize bus throughput.) Once the Stop condition for a Write command has been issued from the master, the device initiates the internally timed write cycle. ACK polling can be initiated immediately. This involves the master sending a Start condition, followed by the control byte for a Write command (R/$\overline{W}$ = 0). If the device is still busy with the write cycle, then no ACK will be returned. If no ACK is returned, then the Start bit and control byte must be resent. If the cycle is complete, then the device will return the ACK, and the master can then proceed with the next Read or Write command. See Figure 7-1 for flow diagram.

Note:	Care must be taken when polling the 24LC515. The control byte that was used to initiate the write needs to match the control byte used for polling.

FIGURE 7-1: ACKNOWLEDGE POLLING FLOW



© 2005 Microchip Technology Inc.

8.0 READ OPERATION

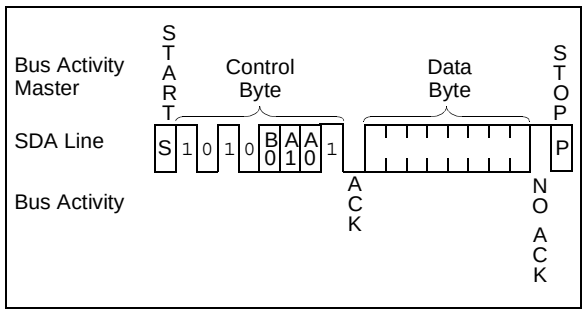
Read operations are initiated in the same way as write operations with the exception that the R/$\overline{W}$ bit of the control byte is set to one. There are three basic types of read operations: current address read, random read and sequential read.

8.1 Current Address Read

The 24XX515 contains an address counter that maintains the address of the last word accessed, internally incremented by one. Therefore, if the previous read access was to address n (n is any legal address), the next current address read operation would access data from address n + 1.

Upon receipt of the control byte with R/$\overline{W}$ bit set to one, the 24XX515 issues an acknowledge and transmits the 8-bit data word. The master will not acknowledge the transfer, but does generate a Stop condition and the 24XX515 discontinues transmission (Figure 8-1).

FIGURE 8-1: CURRENT ADDRESS READ



8.2 Random Read

Random read operations allow the master to access any memory location in a random manner. To perform this type of read operation, first the word address must be set. This is done by sending the word address to the 24XX515 as part of a write operation (R/$\overline{W}$ bit set to 0). After the word address is sent, the master generates a Start condition following the acknowledge. This terminates the write operation, but not before the internal Address Pointer is set. Then, the master issues the control byte again, but with the R/$\overline{W}$ bit set to a one. The 24XX515 will then issue an acknowledge and transmit the 8-bit data word. The master will not acknowledge the transfer, but does generate a Stop condition which causes the 24XX515 to discontinue transmission (Figure 8-2). After a random Read command, the internal address counter will point to the address location following the one that was just read.

8.3 Sequential Read

Sequential reads are initiated in the same way as a random read except that after the 24XX515 transmits the first data byte, the master issues an acknowledge as opposed to the Stop condition used in a random read. This acknowledge directs the 24XX515 to transmit the next sequentially addressed 8-bit word (Figure 8-3). Following the final byte transmitted to the master, the master will NOT generate an acknowledge, but will generate a Stop condition. To provide sequential reads, the 24XX515 contains an internal Address Pointer which is incremented by one at the completion of each operation. This Address Pointer allows half the memory contents to be serially read during one operation. Sequential read address boundaries are 0000h to 7FFFh and 8000h to FFFFh. The internal Address Pointer will automatically roll over from address 7FFF to address 0000 if the master acknowledges the byte received from the array address 7FFF. The internal address counter will automatically roll over from address FFFFh to address 8000h if the master acknowledges the byte received from the array address FFFFh.

FIGURE 8-2: RANDOM READ

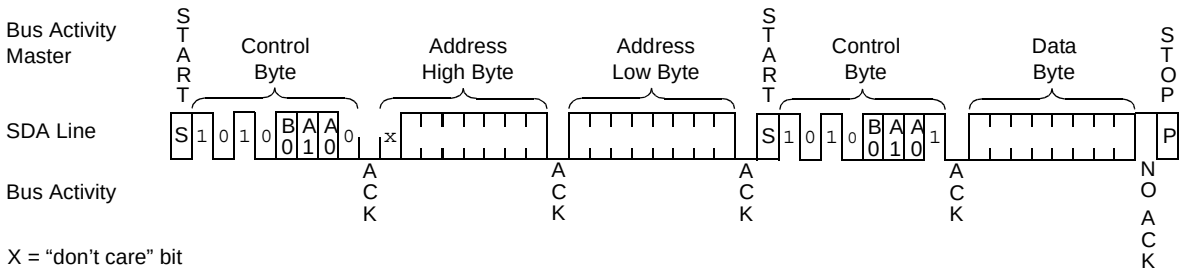
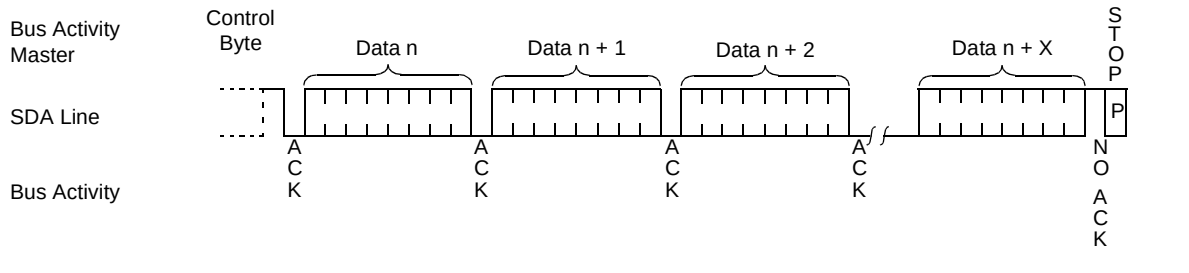


FIGURE 8-3: SEQUENTIAL READ

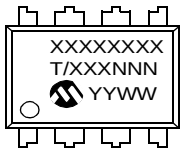


© 2005 Microchip Technology Inc.

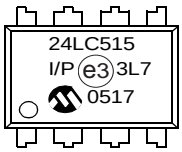
9.0 PACKAGING INFORMATION

9.1 Package Marking Information

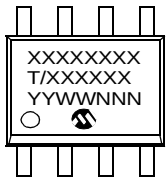
8-Lead PDIP (300 mil)



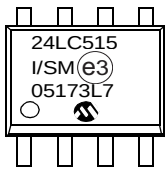
Example:



8-Lead SOIC (208 mil)



Example:



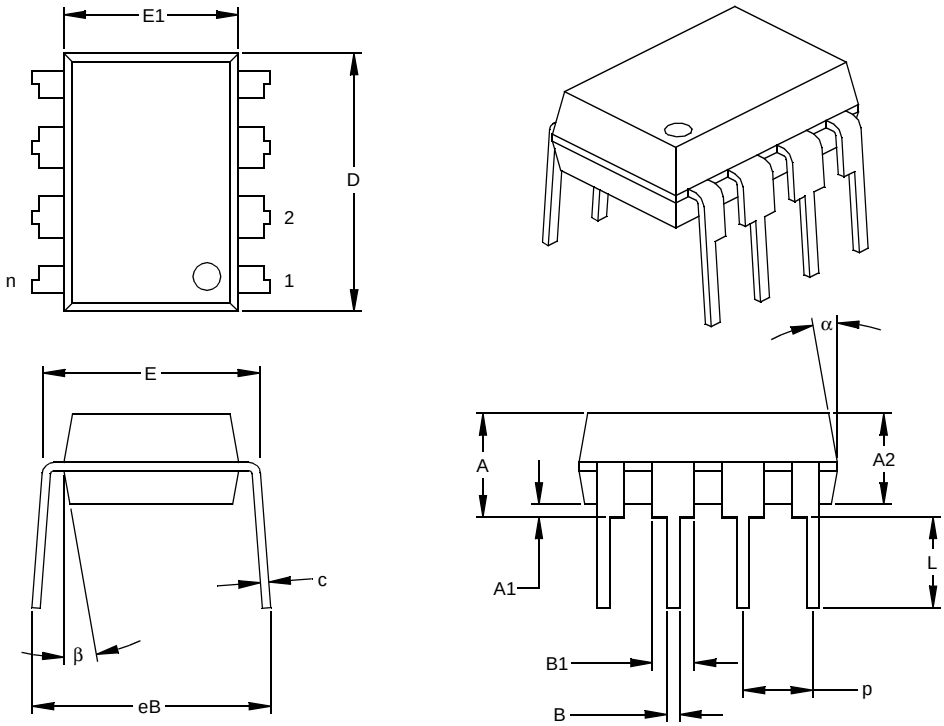
Legend:	XX...X	Part number or part number code
	T	Temperature (I, E)
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code (2 characters for small packages)
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)

Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

***** Standard marking consists of Microchip part number, year code, week code, traceability code (facility code, mask rev#, and assembly code). For marking beyond this, certain price adders apply. Please check with your Microchip Sales Office.

8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



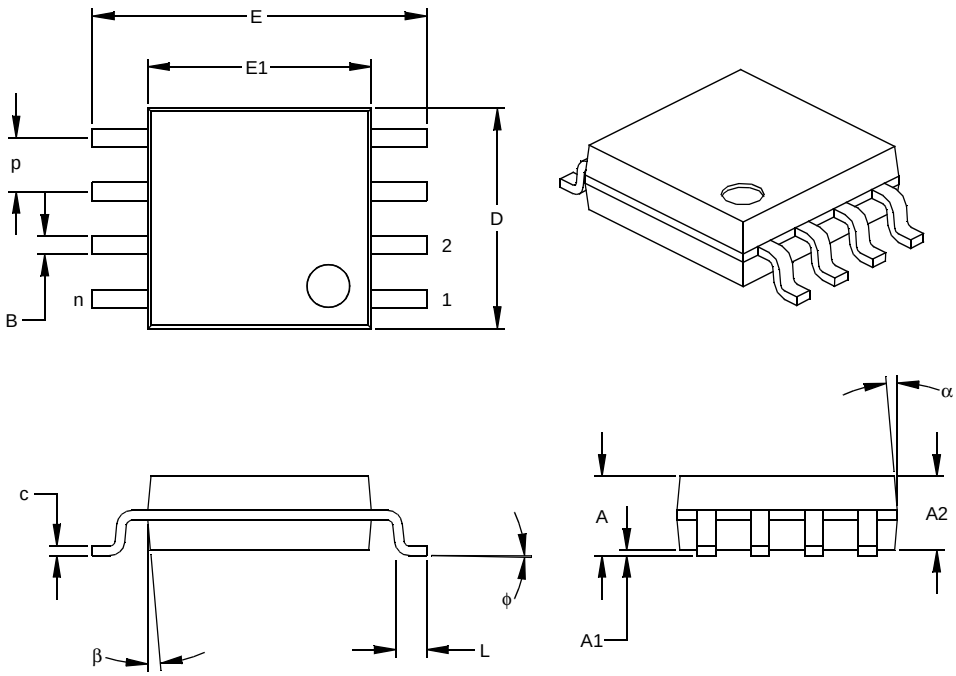
Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-018

© 2005 Microchip Technology Inc.

8-Lead Plastic Small Outline (SM) – Medium, 208 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.070	.075	.080	1.78	1.97	2.03
Molded Package Thickness	A2	.069	.074	.078	1.75	1.88	1.98
Standoff §	A1	.002	.005	.010	0.05	0.13	0.25
Overall Width	E	.300	.313	.325	7.62	7.95	8.26
Molded Package Width	E1	.201	.208	.212	5.11	5.28	5.38
Overall Length	D	.202	.205	.210	5.13	5.21	5.33
Foot Length	L	.020	.025	.030	0.51	0.64	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.014	.017	.020	0.36	0.43	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
Drawing No. C04-056

APPENDIX A: REVISION HISTORY

Revision C

Corrections to Section 1.0, Electrical Characteristics.

Revision D

Removed Preliminary status.
Revised conditions, Table 1-2, Param. 18.

Revision E

Revised Tables 1-1 and 2-1. Add Pb-free marking.

Revision F

Section 1.0 Electrical Characteristics: revised Ambient Temperature; Revised Section 2.1 and Section 2.5

© 2005 Microchip Technology Inc.

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com, click on Customer Change Notification and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support
- Development Systems Information Line

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://support.microchip.com

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

To: Technical Publications Manager Total Pages Sent _____

RE: Reader Response

From: Name _____

Company _____

Address _____

City / State / ZIP / Country _____

Telephone: (_____) _____ - _____ FAX: (_____) _____ - _____

Application (optional):

Would you like a reply? ___Y ___N

Device: 24AA515/24LC515/24FC515 Literature Number: DS21673F

Questions:

1. What are the best features of this document?

2. How does this document meet your hardware and software development needs?

3. Do you find the organization of this document easy to follow? If not, why?

4. What additions to the document do you think would enhance the structure and subject?

5. What deletions from the document could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?

© 2005 Microchip Technology Inc.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	X
Device	Temperature Range	Package	Lead Finish

Device:	24AA515:	=	512K Bit 1.8V I^2C CMOS Serial EEPROM
	24AA515T:	=	512K Bit 1.8V I^2C CMOS Serial EEPROM (Tape and Reel)
	24LC515:	=	512K Bit 2.5V I^2C CMOS Serial EEPROM
	24LC515T:	=	512K Bit 2.5V I^2C CMOS Serial EEPROM (Tape and Reel)
	24FC515:	=	512K Bit 2.5V I^2C CMOS Serial EEPROM
	24FC515T:	=	512K Bit 2.5V I^2C CMOS Serial EEPROM (Tape and Reel)
Temperature Range:	I	=	-40°C to+85°C
Package:	P	=	Plastic DIP (300 mil Body), 8-lead
	SM	=	Plastic SOIC (208 mil Body), 8-lead
Lead Finish:	Blank	=	Pb-free – Matte Tin **(see Note 1)**
	G	=	Pb-free – Matte Tin only

Examples:

a) 24AA515T-I/SM: Tape and Reel, Industrial Temperature, SOIC package.

b) 24LC515-I/P: Industrial Temperature, PDIP package.

c) 24LC515-I/SM: Industrial Temperature, SOIC package.

d) 24LC515T-I/SM: Tape and Reel, Industrial Temperature, SOIC package.

Note 1: Most products manufactured after January 2005 will have a Matte Tin (Pb-free) finish. Most products manufactured before January 2005 will have a finish of approximately 63% Sn and 37% Pb (Sn/Pb).
Please visit www.microchip.com for the latest information on Pb-free conversion, including conversion date codes.

SALES AND SUPPORT

Data Sheets
Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

New Customer Notification System
Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

NOTES:

© 2005 Microchip Technology Inc.

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE**.** Microchip disclaims all liability arising from this information and its use. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, KEELOQ, microID, MPLAB, PIC, PICmicro, PICSTART, PRO MATE, PowerSmart, rfPIC, and SmartShunt are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AmpLab, FilterLab, Migratable Memory, MXDEV, MXLAB, PICMASTER, SEEVAL, SmartSensor and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, dsPICDEM, dsPICDEM.net, dsPICworks, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, Linear Active Thermistor, MPASM, MPLIB, MPLINK, MPSIM, PICkit, PICDEM, PICDEM.net, PICLAB, PICtail, PowerCal, PowerInfo, PowerMate, PowerTool, rfLAB, rfPICDEM, Select Mode, Smart Serial, SmartTel, Total Endurance and WiperLock are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2005, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
ISO/TS 16949:2002

Microchip received ISO/TS-16949:2002 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona and Mountain View, California in October 2003. The Company's quality system processes and procedures are for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
http://support.microchip.com
Web Address:
www.microchip.com

Atlanta
Alpharetta, GA
Tel: 770-640-0034
Fax: 770-640-0307

Boston
Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago
Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Dallas
Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit
Farmington Hills, MI
Tel: 248-538-2250
Fax: 248-538-2260

Kokomo
Kokomo, IN
Tel: 765-864-8360
Fax: 765-864-8387

Los Angeles
Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

San Jose
Mountain View, CA
Tel: 650-215-1444
Fax: 650-961-0286

Toronto
Mississauga, Ontario,
Canada
Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Australia - Sydney
Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing
Tel: 86-10-8528-2100
Fax: 86-10-8528-2104

China - Chengdu
Tel: 86-28-8676-6200
Fax: 86-28-8676-6599

China - Fuzhou
Tel: 86-591-8750-3506
Fax: 86-591-8750-3521

China - Hong Kong SAR
Tel: 852-2401-1200
Fax: 852-2401-3431

China - Qingdao
Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai
Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang
Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen
Tel: 86-755-8203-2660
Fax: 86-755-8203-1760

China - Shunde
Tel: 86-757-2839-5507
Fax: 86-757-2839-5571

China - Wuhan
Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian
Tel: 86-29-8833-7250
Fax: 86-29-8833-7256

ASIA/PACIFIC

India - Bangalore
Tel: 91-80-2229-0061
Fax: 91-80-2229-0062

India - New Delhi
Tel: 91-11-5160-8631
Fax: 91-11-5160-8632

India - Pune
Tel: 91-20-2566-1512
Fax: 91-20-2566-1513

Japan - Yokohama
Tel: 81-45-471- 6166
Fax: 81-45-471-6122

Korea - Gumi
Tel: 82-54-473-4301
Fax: 82-54-473-4302

Korea - Seoul
Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Penang
Tel: 604-646-8870
Fax: 604-646-5086

Philippines - Manila
Tel: 632-634-9065
Fax: 632-634-9069

Singapore
Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu
Tel: 886-3-572-9526
Fax: 886-3-572-6459

Taiwan - Kaohsiung
Tel: 886-7-536-4818
Fax: 886-7-536-4803

Taiwan - Taipei
Tel: 886-2-2500-6610
Fax: 886-2-2508-0102

Thailand - Bangkok
Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Weis
Tel: 43-7242-2244-399
Fax: 43-7242-2244-393

Denmark - Copenhagen
Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Munich
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy - Milan
Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands - Drunen
Tel: 31-416-690399
Fax: 31-416-690340

Spain - Madrid
Tel: 34-91-352-30-52
Fax: 34-91-352-11-47

UK - Wokingham
Tel: 44-118-921-5869
Fax: 44-118-921-5820

08/24/05

© 2005 Microchip Technology Inc.